

Initial Product/Process Change Notification Document #: IPCN25084X Issue Date: 14 Dec 2022

Assembly & Test site transfer of PQFN-8 3.3 X 3.3 products from onsemi Cebu/Philippines to UTAC Bangkok/Thailand.		
12 Jun 2023 or earlier if approved by customer		
Contact your local onsemi Sales Office or CheePin.Tay@onsemi.com		
Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.		
This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact < <u>PCN.Support@onsemi.com</u> >		
Affected parts are to be identified by site code/date-code		
Test Change, Assembly Change		
Manufacturing Site Transfer		
	External Foundry/Subcon Sites	
	UTAC, Thailand	
	Assembly & UTAC Bangk 12 Jun 2023 Contact you Sample requ Initial PCN o Samples del packing/labo This is an Ir advance not change deta The compl Product/Pro Product/Pro change. In c Affected part Test Change	

Description and Purpose:

The purpose of this change qualification is to transfer Assembly & Test from onsemi Cebu, Philippines to UTAC, Thailand (subcon) for PQFN-8 3.3 X 3.3 products.

After the qualification cycle is completed, these 3 products will be fully manufactured by UTAC, Thailand.

	Before Change Description	After Change Description
Assembly Site	onsemi Cebu, Philippines (PBB)	UTAC, Thailand (UTL1)
Test Site	onsemi Cebu, Philippines (PBB)	UTAC, Thailand (UTL3)
LeadFrame	LF PQFN 8L C194 etched Etch Cu Ag plating	
Bond Wire	Cu 2.0 mil	AuPdCu 2.0 mil

There is no change in product (wafer/die), assembly process, test coverage, datasheet & device marking format as the result of this change and it will not affect the form, fit & function of the products.

onsemi

Qualification Plan:

QV DEVICE NAME: FDMC6686P PACKAGE: PQFN-8 3.3 X 3.3

Test	Specification	Condition	Interval
HTRB	JESD22-A108	Ta=150°C, Vds=-16V, 80% of max rated V	1008 hrs
HTGB	JESD22-A108	Ta=150°C, Vgs=-8V, 100% of max rated V	1008 hrs
HTSL	JESD22-A103	Ta=150°C	1008 hrs
РС	J-STD-020 JESD-A113	MSL 1 @ 260 °C	-
HAST+PC	JESD22-A110	Temp=130°C, 85% RH, ~18.8 psig, Vds=-16V, 80% of max rated V	192 hrs
TC+PC	JESD22-A104	Ta= -55°C to +150°C	1000 сус
uHAST+PC	JESD22-A118	Temp=130°C, 85% RH, ~18.8 psig, unbiased	96 hrs
IOL	MIL-STD-750, (M1037) AEC-Q101	Ta=+25°C, delta Tj=100°C On/off = 2 min	15000 cyc

Estimated date for qualification completion: 27 February 2023

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
FDMC6696P	FDMC6686P
FDMC6688P	FDMC6686P
FDMC6686P	FDMC6686P